

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC020N03MS G	**Issued**	12. May 2021
MA#	MA001716670		
Package	PG-TDSON-8-39	**Weight***	113.30 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.944	2.60	2.60	25983	25983
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.049	0.04		430	
	non noble metal	copper	7440-50-8	48.649	42.96	43.01	429379	429938
wire	non noble metal	copper	7440-50-8	0.039	0.03	0.03	344	344
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		710	
	plastics	epoxy resin	-	6.353	5.61		56075	
	inorganic material	silicondioxide	60676-86-0	33.778	29.81	35.49	298120	354905
leadfinish	non noble metal	tin	7440-31-5	1.520	1.34	1.34	13416	13416
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1398	1398
solder	non noble metal	tin	7440-31-5	0.053	0.05		465	
	noble metal	silver	7440-22-4	0.066	0.06		581	
	non noble metal	lead	7439-92-1	2.516	2.22	2.33	22204	23250
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.150	0.13		1324	
	non noble metal	copper	7440-50-8	16.910	14.92	15.06	149248	150766
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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